

WHAT IS CLAIMED IS:

1. An anisotropically conductive adhesive, comprising:
crushable microcapsules, that each enclose a first substance and a conductive particle; and
a second substance that is curable by a reaction with the first substance, the microcapsules being dispersed in the second substance.
2. An anisotropically conductive adhesive, comprising:
conductive particles, crushable microcapsules, that each enclose a first substance that adheres to each of the conductive particles; and
a second substance that is curable by a reaction with the first substance, the conductive particles being dispersed in the second substance.
3. The anisotropically conductive adhesive according to Claim 1,
the first substance being any substance or mixture of amines, imidazoles, acid anhydrides, and phenols; and
the second substance being an uncured epoxy resin.
4. The anisotropically conductive adhesive according to Claim 1,
the first substance being an uncured epoxy resin; and
the second substance being any substance or mixture of amines, imidazoles, acid anhydrides, and phenols.
5. The anisotropically conductive adhesive according to Claim 1, capsule walls of the microcapsules comprising a thermoplastic resin.
6. The anisotropically conductive adhesive according to Claim 1, the second substance containing a third substance that is curable by a reaction with the second substance, the reaction occurring by heating.
7. A mounting method, comprising:
applying the anisotropically conductive adhesive according to Claim 1 onto either mounting surface of a pair of mounting components; and
pressing the pair of mounting components to crush the microcapsules between mounting conductors provided on the pair of mounting components, the mounting conductors holding the conductive particles and being bonded with each other.
8. A mounting method, comprising:
applying the anisotropically conductive adhesive according to Claim 4 onto either mounting surface of a pair of mounting components;

pressing the pair of mounting components to crush the microcapsules between mounting conductors provided on the pair of mounting components, the mounting conductors holding the conductive particles and being bonded with each other; and

curing the anisotropically conductive adhesive by heating to bond the pair of mounting components with each other.

9. An electro-optical device module manufactured by the mounting method according to Claim 7,

one of the pair of mounting components being a substrate having display elements and constituting a part of an electro-optical device; and

the other of the pair of mounting components being a substrate on which a drive device for the display elements is mounted.

10. An electronic device manufactured by the mounting method according to Claim 7.

11. The anisotropically conductive adhesive according to Claim 2,
the first substance being any substance or mixture of amines, imidazoles, acid anhydrides, and phenols; and

the second substance being an uncured epoxy resin.

12. The anisotropically conductive adhesive according to Claim 2,
the first substance being an uncured epoxy resin; and
the second substance being any substance or mixture of amines, imidazoles, acid anhydrides, and phenols.

13. The anisotropically conductive adhesive according to Claim 2, capsule walls of the microcapsules comprising a thermoplastic resin.

14. The anisotropically conductive adhesive according to Claim 2, the second substance containing a third substance that is curable by a reaction with the second substance, the reaction occurring by heating.

15. A mounting method, comprising:
applying the anisotropically conductive adhesive according to Claim 2 onto either mounting surface of a pair of mounting components; and
pressing the pair of mounting components to crush the microcapsules between mounting conductors provided on the pair of mounting components, the mounting conductors holding the conductive particles and being bonded with each other.

16. An electro-optical device module manufactured by the mounting method according to Claim 8,

one of the pair of mounting components being a substrate having display elements and constituting a part of an electro-optical device; and

the other of the pair of mounting components being a substrate on which a drive device for the display elements is mounted.

17. An electronic device manufactured by the mounting method according to Claim 8.